

Title (en)

NEW METHOD OF FORMING FINE CIRCUIT LINES

Title (de)

NEUES VERFAHREN ZUR HERSTELLUNG FEINER LEITERBAHNEN

Title (fr)

NOUVEAU PROCEDE DE FORMATION DE FINES LIGNES DE CIRCUIT

Publication

EP 0868837 A1 19981007 (EN)

Application

EP 97924540 A 19970501

Priority

- US 9707191 W 19970501
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Abstract (en)

[origin: WO9741713A1] A new method of forming circuit lines on a substrate by applying conductive metal(s) using copper foil as a carrier. The copper foil is etched away, leaving the conductive metals embedded in the surface of the substrate. A photoresist is used to expose trenches which define the desired circuit and copper is applied onto the exposed conductive metals. The method is particularly suited to manufacturing the outer layers of multi-layer circuit boards.

IPC 1-7

H05K 3/02; **H05K 3/10**

IPC 8 full level

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CPC (source: EP)

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Citation (search report)

See references of WO 9741713A1

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